

Title (en)

HIGH-IMPACT POLYSTYRENE RESIN COMPOSITION

Title (de)

SCHLAGFESTE POLYSTYROLHARZZUSAMMENSETZUNG

Title (fr)

COMPOSITION DE RESINE DE POLYSTYRENE EXTREMEMENT RESISTANTE AUX CHOCS

Publication

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Application

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Priority

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Abstract (en)

[origin: EP0733675A1] The present invention relates to an impact resistant polystyrene composition which comprises 5 to 97% by weight of an (a) styrenic polymer having syndiotactic configuration, 2 to 95% by weight of a (b) rubbery elastomer having an olefinic component or a polyolefin, and 0.5 to 10% by weight of a (c) styrene/olefin block or graft copolymer having a micro-phase separation temperature of 180 DEG C at the highest when diluted with dioctyl phthalate to a solution with a concentration of 60% by weight. According to the present invention, an impact resistant polystyrene composition can be provided which is greatly enhanced in impact resistance and extensibility without impairing heat resistance and modulus of elasticity.

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Citation (search report)

- [X] EP 0318793 A1 19890607 - IDEMITSU KOSAN CO [JP]
- [X] EP 0324398 A1 19890719 - IDEMITSU KOSAN CO [JP]
- See references of WO 9611233A1

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